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TITLE: ELECTROLESS TIN PLATING METHOD

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INVENTOR-INFORMATION:

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ABSTRACT:

PURPOSE: To enhance reliability in mounting a multi-pin TAB tape, etc., by treating the surface of a material to be plated with a liq. mixture of the acid, peroxide and org. high molecular compd. and then electroless-plating the material.

CONSTITUTION: Copper as a material to be plated is electroless-plated with tin. In this case, the surface of the material is treated with a liq. mixture of the acid, peroxide and org. high molecular compd., and then the material is electroless-plated. The plated material is further annealed. A soln. contg. at least one kind among sulfuric acid, hydrochloric acid, nitric acid and phosphoric acid is used as the acid. Ammonium persulfate or hydrogen peroxide is used as the peroxide. A compd. obtained by linking a straight-chain hydrocarbon or cyclic-carbon compd. to the sulfate-group or phosphate group or the salt of the compd. are used as the org. compd. Consequently, any trouble is hardly caused in the electric-component circuit.

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